

3. (New) The layered thermal component of claim 2, wherein the at least one thermal interface component further comprises at least one crosslinker moiety, at least one crosslinking compound or at least one crosslinking resin.
4. (New) The layered thermal component of claim 3, wherein the at least one crosslinker moiety, the at least one crosslinking compound or the at least one crosslinking resin comprises an amine resin or an amine-based compound.
5. (New) The layered thermal component of claim 1, wherein the at least one rubber compound comprises at least one secondary, tertiary or otherwise internal hydroxyl group.
6. (New) The layered thermal component of claim 1, wherein the at least one thermal interface component comprises at least one solder material.
7. (New) The layered thermal component of claim 1, wherein the at least one heat spreader component comprises at least one metal or metal-based base material.
8. (New) A method of forming a layered thermal component, comprising:
 - providing at least one thermal interface component, wherein the thermal interface component comprises at least one rubber compound having at least one terminal hydroxyl group and at least one thermally conductive filler material;
 - providing at least one heat spreader component; and
 - coupling the at least one thermal interface component to the at least one heat spreader component.
9. (New) The method of claim 8, wherein the at least one thermal interface component comprises a crosslinkable material.
10. (New) The method of claim 9, wherein the at least one thermal interface component further comprises at least one crosslinker moiety, at least one crosslinking compound or at least one crosslinking resin.
11. (New) The method of claim 10, wherein the at least one crosslinker moiety, the at least one crosslinking compound or the at least one crosslinking resin comprises an amine resin or an amine-based compound.

12. (New) The method of claim 8, wherein the at least one rubber compound comprises at least one secondary, tertiary or otherwise internal hydroxyl group.
13. (New) The method of claim 8, wherein the at least one thermal interface component comprises at least one solder material.
14. (New) The method of claim 8, wherein the at least one thermal interface component further comprises at least one resin component.
15. (New) The method of claim 11, further comprising a crosslinking additive.
16. (New) The method of claim 15, wherein the crosslinking additive comprises a siloxane compound.
17. (New) The method of claim 8, wherein the at least one heat spreader component comprises at least one metal or metal-based base material.
18. (New) A semiconductor component comprising the layered thermal component of claim 1.
19. (New) A semiconductor component comprising the layered thermal component of claim 8.
20. (New) A method for forming the thermal interface component of claim 1 or claim 8, comprising:
 - providing at least one saturated rubber compound;
 - providing at least one amine resin;
 - crosslinking the at least one saturated rubber compound and the at least one amine resin to form a crosslinked rubber-resin mixture;
 - adding at least one thermally conductive filler to the crosslinked rubber-resin mixture; and
 - adding a wetting agent to the crosslinked rubber-resin mixture.

IN THE SPECIFICATION

Insert the following before "Field of the Invention":

This application is a national phase application of application Serial Number PCT/US03/22710, filed July 15, 2003, which claims priority to Serial Number 60/396294, filed July 15, 2002 which are incorporated herein by reference in its entirety.